

**AMENDMENTS TO THE CLAIMS**

This listing of claims replaces all prior versions, and listings, of claims in the application:

1. (cancelled):

2. (cancelled):

3. (cancelled):

4. (cancelled):

5. (cancelled):

6. (cancelled):

7. (cancelled):

8. (cancelled):

9. (cancelled):

10. (cancelled):

11. (cancelled):

12. (cancelled):

13. (New): A chip card comprising:

a chip card body having at least one recess formed therein;

a conductor track supporting layer for laminating inside the chip card;

at least one conductor track connected to the conductor track supporting layer by a screen printing paste, or high-viscosity liquid; and

at least one connecting area associated with each of said at least one conductor track

wherein the conductor track supporting layer has, in the region of the connecting areas, indentations which are filled with the conductive paste, screen printing paste or the high-viscosity liquid,

wherein the conductor track supporting layer is formed of a plurality of sublayers stacked atop each other and bonded to each other,

wherein at least two of the sublayers each have at least one through-hole formed therein,

wherein the through-hole of a first of the plurality of sublayers is in fluid communication with a through-hole formed in a second of the plurality of sublayers,  
wherein the at least one recess is adapted to receive a chip module and/or other electronic component,  
wherein the at least one recess is formed in a side of the conductor track supporting layer which is not coated with the at least one conductor track, and  
wherein the recess has a depth such that a bottom of the recess reaches far enough into the conductor track supporting layer that at least one of the indentations filled with screen printing paste are exposed to the recess.

14. (New): The chip card as claimed in claim 13, wherein the indentations are made as through-holes with an opening on a rear side of the conductor track supporting layer opposite the at least one conductor track.

15. (New): The chip card as claimed in claim 12, further comprising:  
a protective film provide on the rear side of the conductive track support layer.

16. (New): The chip card as claimed in claim 13, wherein the at least one conductor track has the form and function of a coil.

17. (New): The chip card as claimed in claim 13, wherein the screen printing paste has a silver particle content of between 70 and 80% percent by volume.

18. (New): The chip card as claimed in claim 17, wherein the grain size of the silver particles is greater than 45  $\mu\text{m}$ .

19. (New): The chip card as claimed in claim 13, wherein the screen printing paste is conductive.

20. (New): The chip card as claimed in claim 13, wherein the high-viscosity liquid is conductive.